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Understanding Embedded - Microprocessors

Embedded microprocessors are specialized computing chips designed to perform specific tasks within an embedded system. Unlike general-purpose microprocessors found in personal computers, embedded microprocessors are tailored for dedicated functions within larger systems, offering optimized performance, efficiency, and reliability. These microprocessors are integral to the operation of countless electronic devices, providing the computational power necessary for controlling processes, handling data, and managing communications.

Applications of **Embedded - Microprocessors**

Embedded microprocessors are utilized across a broad spectrum of applications, making them indispensable in

Details

E·XF

2	
Product Status	Active
Core Processor	MPC8xx
Number of Cores/Bus Width	1 Core, 32-Bit
Speed	133MHz
Co-Processors/DSP	Communications; CPM
RAM Controllers	DRAM
Graphics Acceleration	No
Display & Interface Controllers	-
Ethernet	10Mbps (1), 10/100Mbps (1)
SATA	-
USB	-
Voltage - I/O	3.3V
Operating Temperature	0°C ~ 95°C (TA)
Security Features	-
Package / Case	357-BBGA
Supplier Device Package	357-PBGA (25x25)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mpc859tzp133a

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



Features

Table 1 shows the functionality supported by the members of the MPC866/859 family.

2 Features

Part	Ca	iche	Ethe	ernet	scc	SMC
Fait	Instruction	Data	10T	10/100	300	SWC
MPC866P	16 Kbytes	8 Kbytes	Up to 4	1	4	2
MPC866T	4 Kbytes	4 Kbytes	Up to 4	1	4	2
MPC859P	16 Kbytes	8 Kbytes	1	1	1	2
MPC859T	4 Kbytes	4 Kbytes	1	1	1	2
MPC859DSL	4 Kbytes	4 Kbytes	1	1	1 ¹	1 ²
MPC852T ³	4 KBytes	4 Kbytes	2	1	2	1

Table 1. MPC866 Family Functionality

¹ On the MPC859DSL, the SCC (SCC1) is for ethernet only. Also, the MPC859DSL does not support the Time Slot Assigner (TSA).

² On the MPC859DSL, the SMC (SMC1) is for UART only.

³ For more details on the MPC852T, please refer to the MPC852T Hardware Specifications.

The following list summarizes the key MPC866/859 features:

- Embedded single-issue, 32-bit PowerPCTM core (implementing the PowerPC architecture) with thirty-two 32-bit general-purpose registers (GPRs)
 - The core performs branch prediction with conditional prefetch, without conditional execution
 - 4- or 8-Kbyte data cache and 4- or 16-Kbyte instruction cache (see Table 1)
 - 16-Kbyte instruction cache (MPC866P and MPC859P) is four-way, set-associative with 256 sets;
 4-Kbyte instruction cache (MPC866T, MPC859T, and MPC859DSL) is two-way, set-associative with 128 sets.
 - 8-Kbyte data cache (MPC866P and MPC859P) is two-way, set-associative with 256 sets; 4-Kbyte data cache(MPC866T, MPC859T, and MPC859DSL) is two-way, set-associative with 128 sets.
 - Cache coherency for both instruction and data caches is maintained on 128-bit (4-word) cache blocks
 - Caches are physically addressed, implement a least recently used (LRU) replacement algorithm, and are lockable on a cache block basis.
 - MMUs with 32-entry TLB, fully associative instruction and data TLBs
 - MMUs support multiple page sizes of 4, 16, and 512 Kbytes, and 8 Mbytes; 16 virtual address spaces and 16 protection groups.
 - Advanced on-chip-emulation debug mode
- The MPC866/859 provides enhanced ATM functionality over that of the MPC860SAR. The MPC866/859 adds major new features available in 'enhanced SAR' (ESAR) mode, including the following:
 - Improved operation, administration, and maintenance (OAM) support
 - OAM performance monitoring (PM) support
 - Multiple APC priority levels available to support a range of traffic pace requirements

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Bus Signal Timing

Num	Chavastavistia	33	MHz	40	MHz	50	MHz	66	MHz	Unit
Num	Characteristic	Min	Max	Min	Max	Min	Max	Min	Мах	Unit
B12a	CLKOUT to \overline{TA} , \overline{BI} negation (when driven by the memory controller or PCMCIA interface) (MAX = 0.00 x B1 + 9.00)	2.50	9.00	2.50	9.00	2.50	9.00	2.50	9.00	ns
B13	CLKOUT to \overline{TS} , \overline{BB} High-Z (MIN = 0.25 x B1)	7.60	21.60	6.30	20.30	5.00	19.00	3.80	14.00	ns
B13a	CLKOUT to \overline{TA} , \overline{BI} High-Z (when driven by the memory controller or PCMCIA interface) (MIN = 0.00 x B1 + 2.5)	2.50	15.00	2.50	15.00	2.50	15.00	2.50	15.00	ns
B14	CLKOUT to TEA assertion (MAX = 0.00 x B1 + 9.00)	2.50	9.00	2.50	9.00	2.50	9.00	2.50	9.00	ns
B15	CLKOUT to $\overline{\text{TEA}}$ High-Z (MIN = 0.00 x B1 + 2.50)	2.50	15.00	2.50	15.00	2.50	15.00	2.50	15.00	ns
B16	\overline{TA} , \overline{BI} valid to CLKOUT (setup time) (MIN = 0.00 x B1 + 6.00)	6.00	-	6.00	—	6.00	—	6.00	—	ns
B16a	TEA, KR, RETRY, CR valid to CLKOUT (setup time) (MIN = 0.00 x B1 + 4.5)	4.50	_	4.50	_	4.50	_	4.50	—	ns
B16b	$\overline{\text{BB}}$, $\overline{\text{BG}}$, $\overline{\text{BR}}$, valid to CLKOUT (setup time) ² (4 MIN = 0.00 x B1 + 0.00)	4.00	—	4.00	—	4.00	_	4.00	—	ns
B17	CLKOUT to \overline{TA} , \overline{TEA} , \overline{BI} , \overline{BB} , \overline{BG} , \overline{BR} valid (hold time) (MIN = 0.00 x B1 + 1.00 ³)	1.00	—	1.00	_	1.00	—	2.00	_	ns
B17a	CLKOUT to $\overline{\text{KR}}$, $\overline{\text{RETRY}}$, $\overline{\text{CR}}$ valid (hold time) (MIN = 0.00 x B1 + 2.00)	2.00	—	2.00	—	2.00	_	2.00	—	ns
B18	D(0:31), DP(0:3) valid to CLKOUT rising edge (setup time) 4 (MIN = 0.00 x B1 + 6.00)	6.00	_	6.00	_	6.00	—	6.00	—	ns
B19	CLKOUT rising edge to D(0:31), DP(0:3) valid (hold time) 4 (MIN = 0.00 x B1 + 1.00 5)	1.00	_	1.00	_	1.00	_	2.00	_	ns
B20	D(0:31), DP(0:3) valid to CLKOUT falling edge (setup time) 6 (MIN = 0.00 x B1 + 4.00)	4.00	—	4.00	—	4.00	—	4.00	—	ns
B21	CLKOUT falling edge to D(0:31), DP(0:3) valid (hold Time) 6 (MIN = 0.00 x B1 + 2.00)	2.00	—	2.00	—	2.00	—	2.00	—	ns
B22	CLKOUT rising edge to \overline{CS} asserted GPCM ACS = 00 (MAX = 0.25 x B1 + 6.3)	7.60	13.80	6.30	12.50	5.00	11.30	3.80	10.00	ns
B22a	CLKOUT falling edge to \overline{CS} asserted GPCM ACS = 10, TRLX = 0 (MAX = 0.00 x B1 + 8.00)		8.00	—	8.00		8.00	—	8.00	ns

Table 9. Bus Operation Timings (continued)



	Ohann sharia tia	33	MHz	40 I	MHz	50 I	MHz	66 I	MHz	
Num	Characteristic	Min	Max	Min	Мах	Min	Max	Min	Max	Unit
B22b	CLKOUT falling edge to \overline{CS} asserted GPCM ACS = 11, TRLX = 0, EBDF = 0 (MAX = 0.25 x B1 + 6.3)	7.60	13.80	6.30	12.50	5.00	11.30	3.80	10.00	ns
B22c	CLKOUT falling edge to \overline{CS} asserted GPCM ACS = 11, TRLX = 0, EBDF = 1 (MAX = 0.375 x B1 + 6.6)	10.90	18.00	10.90	16.00	7.00	14.10	5.20	12.30	ns
B23	CLKOUT rising edge to \overline{CS} negated GPCM read access, GPCM write access ACS = 00, TRLX = 0 & CSNT = 0 (MAX = 0.00 x B1 + 8.00)	2.00	8.00	2.00	8.00	2.00	8.00	2.00	8.00	ns
B24	A(0:31) and BADDR(28:30) to \overline{CS} asserted GPCM ACS = 10, TRLX = 0 (MIN = 0.25 x B1 - 2.00)	5.60	_	4.30	_	3.00	_	1.80	_	ns
B24a	A(0:31) and BADDR(28:30) to \overline{CS} asserted GPCM ACS = 11, TRLX = 0 (MIN = 0.50 x B1 - 2.00)	13.20	—	10.50	—	8.00	—	5.60	—	ns
B25	CLKOUT rising edge to \overline{OE} , $\overline{WE}(0:3)$ asserted (MAX = 0.00 x B1 + 9.00)	—	9.00	—	9.00		9.00		9.00	ns
B26	CLKOUT rising edge to \overline{OE} negated (MAX = 0.00 x B1 + 9.00)	2.00	9.00	2.00	9.00	2.00	9.00	2.00	9.00	ns
B27	A(0:31) and BADDR(28:30) to \overline{CS} asserted GPCM ACS = 10, TRLX = 1 (MIN = 1.25 x B1 - 2.00)	35.90	_	29.30	—	23.00	—	16.90	_	ns
B27a	A(0:31) and BADDR(28:30) to \overline{CS} asserted GPCM ACS = 11, TRLX = 1 (MIN = 1.50 x B1 - 2.00)	43.50	—	35.50	—	28.00	_	20.70	_	ns
B28	CLKOUT rising edge to $\overline{WE}(0:3)$ negated GPCM write access CSNT = 0 (MAX = 0.00 x B1 + 9.00)	—	9.00	—	9.00	_	9.00	—	9.00	ns
B28a	CLKOUT falling edge to $\overline{WE}(0:3)$ negated GPCM write access TRLX = 0,1, CSNT = 1, EBDF = 0 (MAX = 0.25 x B1 + 6.80)	7.60	14.30	6.30	13.00	5.00	11.80	3.80	10.50	ns
B28b	CLKOUT falling edge to \overline{CS} negated GPCM write access TRLX = 0,1, CSNT = 1, ACS = 10 or ACS = 11, EBDF = 0 (MAX = 0.25 x B1 + 6.80)	_	14.30	_	13.00	_	11.80	_	10.50	ns
B28c	CLKOUT falling edge to $\overline{WE}(0:3)$ negated GPCM write access TRLX = 0, CSNT = 1 write access TRLX = 0,1, CSNT = 1, EBDF = 1 (MAX = 0.375 x B1 + 6.6)	10.90	18.00	10.90	18.00	7.00	14.30	5.20	12.30	ns

Table 9. Bus Operation Timings (continued)



Num	Chavastavistia	33 I	MHz	40 N	MHz	50 I	MHz	66 MHz		Unit
num	Characteristic	Min	Max	Min	Max	Min	Max	Min	Мах	Unit
B35	A(0:31), BADDR(28:30) to \overline{CS} valid, as requested by control bit BST4 in the corresponding word in the UPM (MIN = 0.25 x B1 - 2.00)	5.60	_	4.30		3.00		1.80	_	ns
B35a	A(0:31), BADDR(28:30), and D(0:31) to \overline{BS} valid, as Requested by BST1 in the corresponding word in the UPM (MIN = 0.50 x B1 - 2.00)	13.20		10.50		8.00		5.60	_	ns
B35b	A(0:31), BADDR(28:30), and D(0:31) to \overline{BS} valid, as requested by control bit BST2 in the corresponding word in the UPM (MIN = 0.75 x B1 - 2.00)	20.70	_	16.70	_	13.00	_	9.40	_	ns
B36	A(0:31), BADDR(28:30), and D(0:31) to \overline{GPL} valid as requested by control bit GxT4 in the corresponding word in the UPM (MIN = 0.25 x B1 - 2.00)	5.60	_	4.30	_	3.00	_	1.80	_	ns
B37	UPWAIT valid to CLKOUT falling edge ⁸ (MIN = 0.00 x B1 + 6.00)	6.00		6.00		6.00		6.00	—	ns
B38	CLKOUT falling edge to UPWAIT valid ⁸ (MIN = 0.00 x B1 + 1.00)	1.00		1.00	_	1.00		1.00	_	ns
B39	$\overline{\text{AS}}$ valid to CLKOUT rising edge ⁹ (MIN = 0.00 x B1 + 7.00)	7.00		7.00		7.00		7.00	—	ns
B40	A(0:31), TSIZ(0:1), RD/WR, BURST, valid to CLKOUT rising edge (MIN = 0.00 x B1 + 7.00)	7.00	_	7.00	_	7.00	_	7.00	_	ns
B41	$\overline{\text{TS}}$ valid to CLKOUT rising edge (setup time) (MIN = 0.00 x B1 + 7.00)	7.00	_	7.00	_	7.00	_	7.00	_	ns
B42	CLKOUT rising edge to \overline{TS} valid (hold time) (MIN = 0.00 x B1 + 2.00)	2.00	_	2.00	_	2.00	_	2.00	—	ns
B43	$\overline{\text{AS}}$ negation to memory controller signals negation (MAX = TBD)	_	TBD	_	TBD	_	TBD	_	TBD	ns

Table 9. Bus Operation Timings (continued)

¹ For part speeds above 50 MHz, use 9.80 ns for B11a.

² The timing required for BR input is relevant when the MPC866/859 is selected to work with the internal bus arbiter. The timing for BG input is relevant when the MPC866/859 is selected to work with the external bus arbiter.

³ For part speeds above 50 MHz, use 2 ns for B17.

⁴ The D(0:31) and DP(0:3) input timings B18 and B19 refer to the rising edge of CLKOUT, in which the TA input signal is asserted.

⁵ For part speeds above 50 MHz, use 2 ns for B19.

⁶ The D(0:31) and DP(0:3) input timings B20 and B21 refer to the falling edge of CLKOUT. This timing is valid only for read accesses controlled by chip-selects under control of the UPM in the memory controller, for data beats, where DLT3 = 1 in the UPM RAM words. (This is only the case where data is latched on the falling edge of CLKOUT.)

⁷ The timing B30 refers to \overline{CS} when ACS = 00 and to $\overline{WE}(0:3)$ when CSNT = 0.

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Figure 10 shows normal case timing for input data. It also applies to normal read accesses under the control of the UPM in the memory controller.

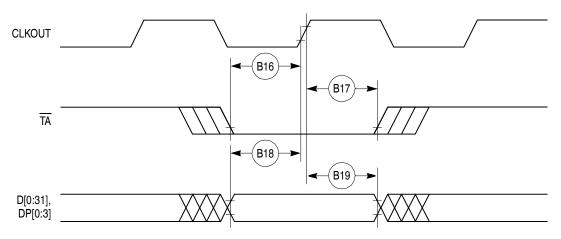


Figure 10. Input Data Timing in Normal Case

Figure 11 shows the timing for the input data controlled by the UPM for data beats where DLT3 = 1 in the UPM RAM words. (This is only the case where data is latched on the falling edge of CLKOUT.)

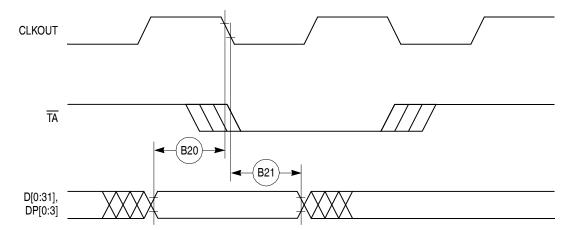


Figure 11. Input Data Timing when Controlled by UPM in the Memory Controller and DLT3 = 1



Figure 16 through Figure 18 show the timing for the external bus write controlled by various GPCM factors.

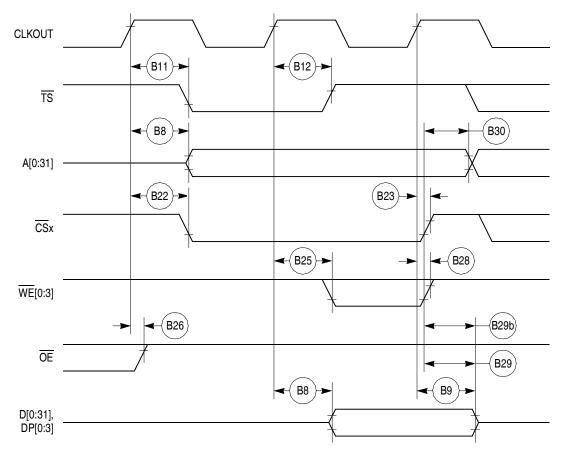


Figure 16. External Bus Write Timing (GPCM Controlled—TRLX = 0 or 1, CSNT = 0)



Bus Signal Timing

Figure 25 shows the interrupt detection timing for the external level-sensitive lines.

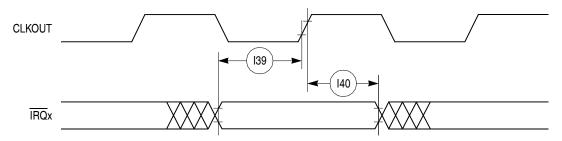


Figure 25. Interrupt Detection Timing for External Level Sensitive Lines

Figure 26 shows the interrupt detection timing for the external edge-sensitive lines.

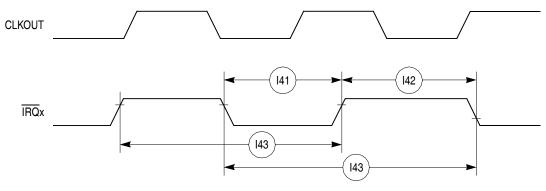


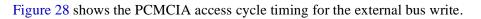
Figure 26. Interrupt Detection Timing for External Edge Sensitive Lines

Table 11 shows the PCMCIA timing for the MPC866/859.

Table 11. PCMCIA Timing

Num	Characteristic	33 I	33 MHz		MHz	50 I	ЛНz	66 I	MHz	Unit
Num	onardotenstie	Min	Мах	Min	Max	Min	Мах	Min	Max	Onit
P44	A(0:31), $\overline{\text{REG}}$ valid to PCMCIA Strobe asserted ¹ (MIN = 0.75 x B1 - 2.00)	20.70	_	16.70	_	13.00	_	9.40	_	ns
P45	A(0:31), $\overline{\text{REG}}$ valid to ALE negation ¹ (MIN = 1.00 x B1 - 2.00)	28.30	_	23.00	_	18.00		13.20	_	ns
P46	CLKOUT to $\overline{\text{REG}}$ valid (MAX = 0.25 x B1 + 8.00)	7.60	15.60	6.30	14.30	5.00	13.00	3.80	11.80	ns
P47	CLKOUT to $\overline{\text{REG}}$ invalid (MIN = 0.25 x B1 + 1.00)	8.60	_	7.30	_	6.00	_	4.80	_	ns
P48	CLKOUT to $\overline{CE1}$, $\overline{CE2}$ asserted (MAX = 0.25 x B1 + 8.00)	7.60	15.60	6.30	14.30	5.00	13.00	3.80	11.80	ns
P49	CLKOUT to $\overline{CE1}$, $\overline{CE2}$ negated (MAX = 0.25 x B1 + 8.00)	7.60	15.60	6.30	14.30	5.00	13.00	3.80	11.80	ns





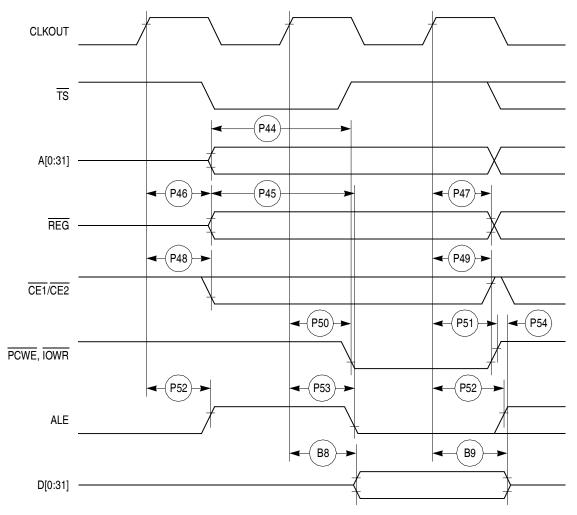


Figure 28. PCMCIA Access Cycles Timing External Bus Write

Figure 29 shows the PCMCIA WAIT signals detection timing.

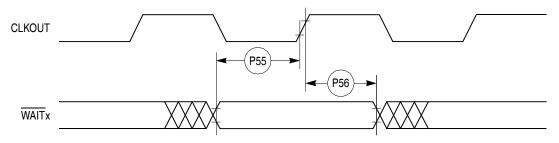


Figure 29. PCMCIA WAIT Signals Detection Timing

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Table 13 shows the debug port timing for the MPC866/859.

Table 13. Debug Port Timing

Num	Characteristic	All Frequenc	ies	Unit
Nulli	Characteristic	Min	Max	Unit
D61	DSCK cycle time	3xT _{CLOCKOUT}		
D62	DSCK clock pulse width	1.25xT _{CLOCKOUT}	_	
D63	DSCK rise and fall times	0.00	3.00	ns
D64	DSDI input data setup time	8.00	_	ns
D65	DSDI data hold time	5.00	_	ns
D66	DSCK low to DSDO data valid	0.00	15.00	ns
D67	DSCK low to DSDO invalid	0.00	2.00	ns

Figure 32 shows the input timing for the debug port clock.

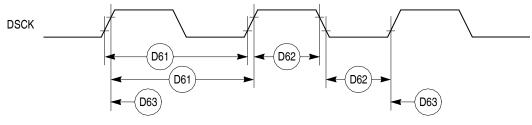


Figure 32. Debug Port Clock Input Timing

Figure 33 shows the timing for the debug port.

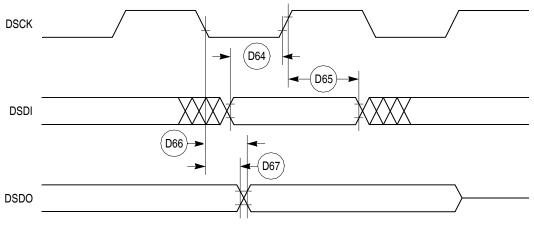


Figure 33. Debug Port Timings



Bus Signal Timing

Table 14 shows the reset timing for the MPC866/859.

Table 14. Reset Timing

	Charactoristic	33 N	/Hz	40 N	/Hz	50 N	/Hz	66 MHz		11
Num	Characteristic	Min	Max	Min	Max	Min	Max	Min	Max	Unit
R69	CLKOUT to $\overline{\text{HRESET}}$ high impedance (MAX = 0.00 x B1 + 20.00)		20.00		20.00		20.00		20.00	ns
R70	CLKOUT to $\overline{\text{SRESET}}$ high impedance (MAX = 0.00 x B1 + 20.00)	—	20.00	—	20.00	—	20.00	—	20.00	ns
R71	RSTCONF pulse width (MIN = 17.00 x B1)	515.20	—	425.00	—	340.00	—	257.60	—	ns
R72	—	—	—	_		_		_	_	—
R73	Configuration data to HRESET rising edge setup time (MIN = 15.00 x B1 + 50.00)	504.50	_	425.00	_	350.00	_	277.30	—	ns
R74	Configuration data to $\overrightarrow{\text{RSTCONF}}$ rising edge setup time (MIN = 0.00 x B1 + 350.00)	350.00		350.00		350.00		350.00		ns
R75	Configuration data hold time after RSTCONF negation (MIN = 0.00 x B1 + 0.00)	0.00		0.00		0.00		0.00		ns
R76	Configuration data hold time after HRESET negation (MIN = 0.00 x B1 + 0.00)	0.00		0.00		0.00		0.00		ns
R77	HRESET and RSTCONF asserted to data out drive (MAX = 0.00 x B1 + 25.00)		25.00		25.00		25.00	_	25.00	ns
R78	RSTCONF negated to data out high impedance (MAX = 0.00 x B1 + 25.00)		25.00		25.00		25.00		25.00	ns
R79	CLKOUT of last rising edge before chip three-states $\overrightarrow{\text{HRESET}}$ to data out high impedance (MAX = 0.00 x B1 + 25.00)		25.00	_	25.00	_	25.00	_	25.00	ns
R80	DSDI, DSCK setup (MIN = 3.00 x B1)	90.90	—	75.00	_	60.00	_	45.50	_	ns
R81	DSDI, DSCK hold time (MIN = 0.00 x B1 + 0.00)	0.00	—	0.00	_	0.00		0.00	_	ns
R82	SRESET negated to CLKOUT rising edge for DSDI and DSCK sample (MIN = 8.00 x B1)	242.40		200.00	—	160.00	—	121.20	—	ns



Figure 34 shows the reset timing for the data bus configuration.

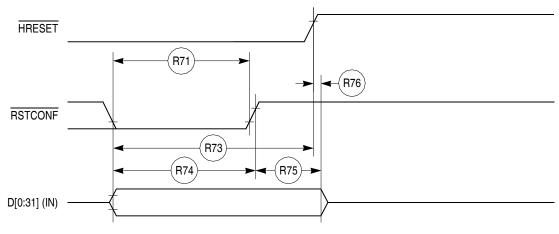


Figure 34. Reset Timing—Configuration from Data Bus

Figure 35 shows the reset timing for the data bus weak drive during configuration.

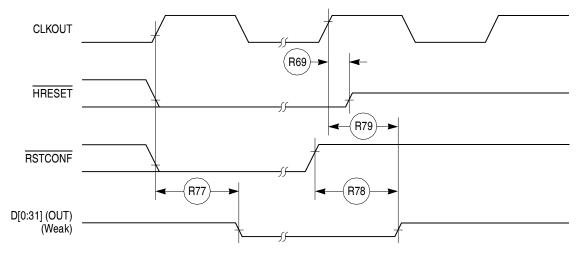
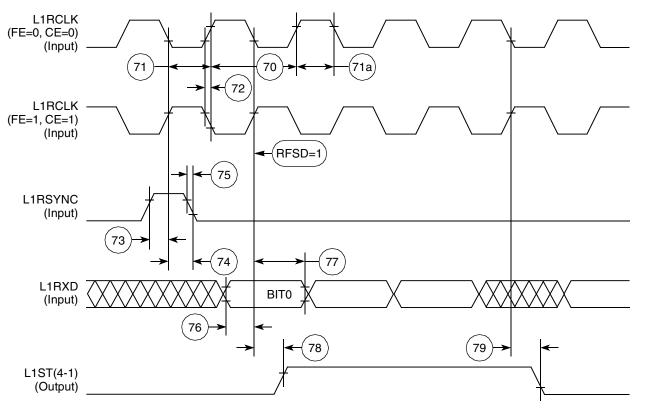


Figure 35. Reset Timing—Data Bus Weak Drive During Configuration



CPM Electrical Characteristics





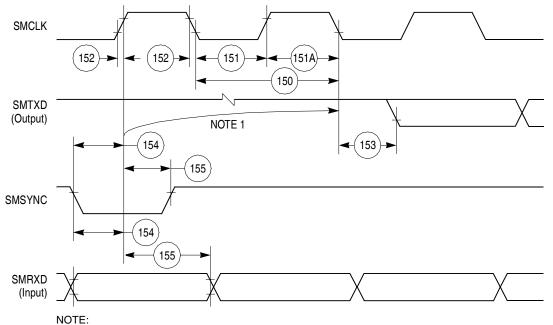


CPM Electrical Characteristics

Num	Characteristic	All Freq	uencies	Unit
Nulli	Characteristic	Min	Мах	Unit
150	SMCLK clock period ¹	100	_	ns
151	SMCLK width low	50	_	ns
151A	SMCLK width high	50	_	ns
152	SMCLK rise/fall time	—	15	ns
153	SMTXD active delay (from SMCLK falling edge)	10	50	ns
154	SMRXD/SMSYNC setup time	20	—	ns
155	RXD1/SMSYNC hold time	5	_	ns
¹ Svnc (CLK must be at least twice as fast as SMCLK.	•		•

Table 25. SMC Transparent Timing

Sync CLK must be at least twice as fast as SMCLK.



1. This delay is equal to an integer number of character-length clocks.

Figure 66. SMC Transparent Timing Diagram



12.10SPI Master AC Electrical Specifications

Table 26 shows the SPI master timings as shown in Figure 67 and Figure 68.

Table 26. SPI Master Timing

Num	Characteristic	All Freq	Unit	
Num	Characteristic	Min	Max	Onit
160	MASTER cycle time	4	1024	t _{cyc}
161	MASTER clock (SCK) high or low time	2	512	t _{cyc}
162	MASTER data setup time (inputs)	15	_	ns
163	Master data hold time (inputs)	0	_	ns
164	Master data valid (after SCK edge)	_	10	ns
165	Master data hold time (outputs)	0	_	ns
166	Rise time output	_	15	ns
167	Fall time output	_	15	ns

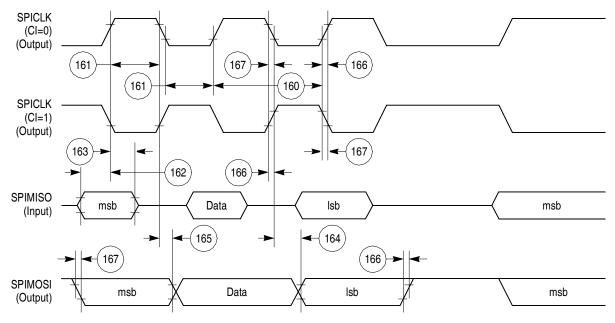


Figure 67. SPI Master (CP = 0) Timing Diagram



Table 28 shows the I^2C (SCL < 100 kHz) timings.

Table 28. I²C Timing (SCL < 100 kHz)

Num	Characteristic	All Freq	uencies	Unit
Num	Characteristic	Min	Max	Unit
200	SCL clock frequency (slave)	0	100	kHz
200	SCL clock frequency (master) ¹	1.5	100	kHz
202	Bus free time between transmissions	4.7		μs
203	Low period of SCL	4.7	_	μs
204	High period of SCL	4.0	_	μs
205	Start condition setup time	4.7		μs
206	Start condition hold time	4.0	_	μs
207	Data hold time	0	_	μs
208	Data setup time	250	_	ns
209	SDL/SCL rise time	—	1	μs
210	SDL/SCL fall time	—	300	ns
211	Stop condition setup time	4.7	—	μs

SCL frequency is given by SCL = BRGCLK_frequency / ((BRG register + 3) * pre_scaler * 2). The ratio SyncClk/(BRGCLK/pre_scaler) must be greater or equal to 4/1.

Table 29 shows the I^2C (SCL > 100 kHz) timings.

Table 29. I^2C Timing (SCL > 100 kHz)

Num	Characteristic	Expression	All Freq	uencies	Unit
num	Characteristic	Expression	Min	Мах	Unit
200	SCL clock frequency (slave)	fSCL	0	BRGCLK/48	Hz
200	SCL clock frequency (master) ¹	fSCL	BRGCLK/16512	BRGCLK/48	Hz
202	Bus free time between transmissions	_	1/(2.2 * fSCL)	_	s
203	Low period of SCL	_	1/(2.2 * fSCL)	_	s
204	High period of SCL	—	1/(2.2 * fSCL)	_	s
205	Start condition setup time	—	1/(2.2 * fSCL)	_	s
206	Start condition hold time	—	1/(2.2 * fSCL)	_	s
207	Data hold time	—	0	_	s
208	Data setup time	—	1/(40 * fSCL)	_	s
209	SDL/SCL rise time	—	—	1/(10 * fSCL)	s
210	SDL/SCL fall time	—	—	1/(33 * fSCL)	s
211	Stop condition setup time	—	1/2(2.2 * fSCL)		s

SCL frequency is given by SCL = BrgClk_frequency / ((BRG register + 3) * pre_scaler * 2). The ratio SyncClk/(Brg_Clk/pre_scaler) must be greater or equal to 4/1.



Num	Signal Characteristic	Direction	Min	Max	Unit
U1	UtpClk rise/fall time (external clock option)	Input		4	ns
	Duty cycle		40	60	%
	Frequency		_	33	MHz
U2	UTPB, SOC, Rxclav and Txclav active delay	Output	2	16	ns
U3	UTPB_AUX, SOC_Aux, RxEnb, TxEnb, RxAddr, and TxAddr setup time	Input	4	—	ns
U4	UTPB_AUX, SOC_Aux, RxEnb, TxEnb, RxAddr, and TxAddr hold time	Input	1	_	ns

Table 32. UTOPIA Slave (Split Bus Mode) Electrical Specifications

Figure 72 shows signal timings during UTOPIA receive operations.

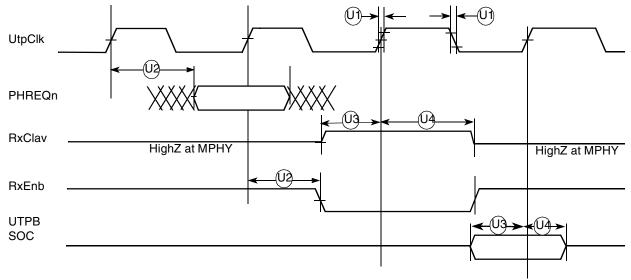


Figure 72. UTOPIA Receive Timing



Mechanical Data and Ordering Information

Name	Pin Number	Туре
BR	G4	Bidirectional
BG	E2	Bidirectional
BB	E1	Bidirectional Active Pull-up
FRZ IRQ6	G3	Bidirectional
IRQ0	V14	Input
IRQ1	U14	Input
M_TX_CLK IRQ7	W15	Input
CS[0:5]	C3, A2, D4, E4, A4, B4	Output
CS6 CE1_B	D5	Output
CS7 CE2_B	C4	Output
WE0 BS_B0 IORD	C7	Output
WE1 BS_B1 IOWR	A6	Output
WE2 BS_B2 PCOE	B6	Output
WE3 BS_B3 PCWE	A5	Output
BS_A[0:3]	D8, C8, A7, B8	Output
GPL_A0 GPL_B0	D7	Output
OE GPL_A1 GPL_B1	C6	Output
GPL_A[2:3] GPL_B[2:3] CS[2-3]	B5, C5	Output
UPWAITA GPL_A4	C1	Bidirectional

Table 39. Pin Assignments (continued)



Mechanical Data and Ordering Information

Table 39	Pin	Assignments	(continued)
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Name	Pin Number	Туре
PC7 CTS3 L1TSYNCB SDACK2	M16	Bidirectional
PC6 CD3 L1RSYNCB	R19	Bidirectional
PC5 CTS4 L1TSYNCA SDACK1	Т18	Bidirectional
PC4 CD4 L1RSYNCA	T17	Bidirectional
PD15 L1TSYNCA MII-RXD3 UTPB0	U17	Bidirectional
PD14 L1RSYNCA MII-RXD2 UTPB1	V19	Bidirectional
PD13 L1TSYNCB MII-RXD1 UTPB2	V18	Bidirectional
PD12 L1RSYNCB MII-MDC UTPB3	R16	Bidirectional
PD11 RXD3 MII-TXERR RXENB	T16	Bidirectional
PD10 TXD3 MII-RXD0 TXENB	W18	Bidirectional



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